This is a published notice on the Find a Tender service: https://www.find-tender.service.gov.uk/Notice/037530-2025

Award

Silicon Wafers for Test Chips

THE OPEN UNIVERSITY

UK5: Transparency notice - Procurement Act 2023 - view information about notice types

Notice identifier: 2025/S 000-037530
Procurement identifier (OCID): ocds-h6vhtk-055960 (view related notices)
Published 4 July 2025, 3:42pm

Scope

Reference

OUPA11504

Description

As part of the existing Technology Development Element (TDE) contract with the European Space Agency (ESA), the Open University (OU), in company with Teledyne-e2v, are required to procure and test three experimental test chips for characterisation and testing.

Phase 1: To procure Silicon wafers for the manufacture of Front Side Illuminated (FSI) soft X-ray Complementary Metal Oxide Semiconductor (CMOS) imaging detectors to characterise their Electro Optical (EO) performance both pre and post irradiation.

Phase 2: A potential second phase subject to funding to process any remaining Silicon wafers from the first phase for the manufacture of Back Side Illuminated (BSI) soft X-ray CMOS imaging detectors to characterise their EO performance both pre and post irradiation.

Phase 3: A potential third phase subject to funding to procure Silicon wafers to manufacture another batch of either FSI or BSI soft X-ray CMOS imaging detectors for further characterisation of their EO performance both pre and post irradiation.

Cost

Phase 1: £220,000

Phase 2: £250,000

Phase 3: £350,00

Total: £820,000

Contract 1. Silicon Wafers for Test Chips

Supplier

- X-FAB

Contract value

- 820000 EUR excluding VAT
- 820000 EUR including VAT

Above the relevant threshold

Earliest date the contract will be signed

18 July 2025

Contract dates (estimated)

- 18 July 2025 to 31 January 2026
- Possible extension to 1 October 2029
- 4 years, 2 months, 15 days

Description of possible extension:

Extension End Date:

Phase 2: March 2028

Phase 3: September 2029

Main procurement category

Goods

CPV classifications

- 38000000 - Laboratory, optical and precision equipments (excl. glasses)

Other information

Conflicts assessment prepared/revised

Yes

Procedure

Procedure type

Direct award

Direct award justification

Single supplier - technical reasons

The following conditions are met in relation to the public contract-

a) due to an absence of competition for technical reasons, only a particular supplier can supply the goods, services or works required, and

b) there are no reasonable alternatives to those goods, services or works.

Teledyne-e2v have previously performed a competitor analysis and based on a comparison of price and technical performance, XFAB were selected as the preferred supplier for all their silicon chip products. As a result, Teledyne's CMOS imaging device design and manufacturing plans for this project have been developed to align with XFAB's design rules and processes. Consequently, in order to meet the requirements of the ESA agreement the OU must procure wafers from XFAB to ensure compatibility with Teledyne's design and manufacturing standards.

Supplier

X-FAB

- Public Procurement Organisation Number: PLGZ-1483-CXTX

1 Silicon Drive, Sama Jaya Free Industrial Zone, Kuching

Sarawak

93350

Malaysia

Telephone: +6082354888

Email: michael.rome@xfab.com

Small or medium-sized enterprise (SME): No

Voluntary, community or social enterprise (VCSE): No

Contract 1. Silicon Wafers for Test Chips

Contracting authority

THE OPEN UNIVERSITY

- Charity Commission (England and Wales): RC000391

Walton Hall

Milton Keynes

MK7 6AA

United Kingdom

Email: finance-tenders@open.ac.uk

Region: UKJ12 - Milton Keynes

Organisation type: Public authority - sub-central government